FRONTGRADE

DATASHEET

UT54ACS85/UT54ACTS85

4-Bit Comparators

11/1/2010

Version #: 1.0

Features

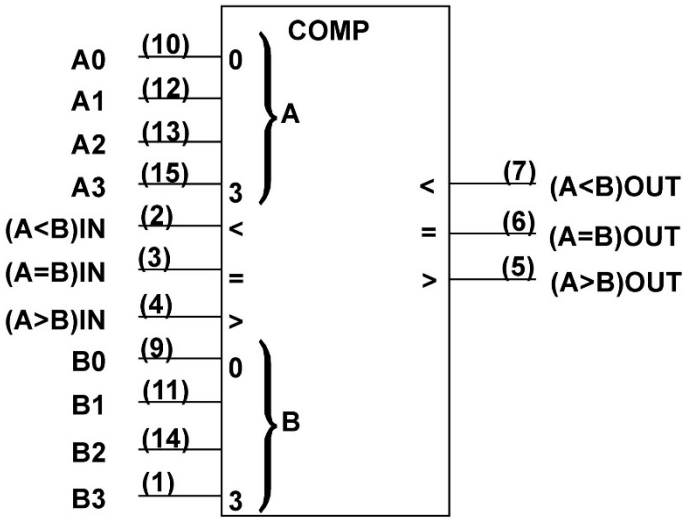
- 1.2µ CMOS
  - > Latchup immune
- High speed
- Low power consumption
- Single 5-volt supply
- Available QML Q or V processes
- Flexible package
  - > 16-pin DIP
  - > 16-lead flatpack
- UT54ACS85 - SMD 5962-96536
- UT54ACTS85 - SMD 5962-96537

Description

The UT54ACS85 and the UT54ACTS85 are 4-bit magnitude comparators that perform comparison of straight binary and straight BCD (8-4-2-1) codes. Three fully decoded decisions about two 4-bit words (A, B) are made and are externally available at three outputs. Devices are fully expandable to any number of bits without external gates. The cascading paths of the devices are implemented with only a two-gate-level delay to reduce overall comparison times for long words. An alternate method of cascading which further reduces the comparison time is shown in the typical application data.

The devices are characterized over full military temperature range of -55°C to +125°C.

Logic Symbol



Note:

1. Logic symbol in accordance with ANSI/IEEE standard 91-1984 and IEC Publication 617-12.

Pinouts

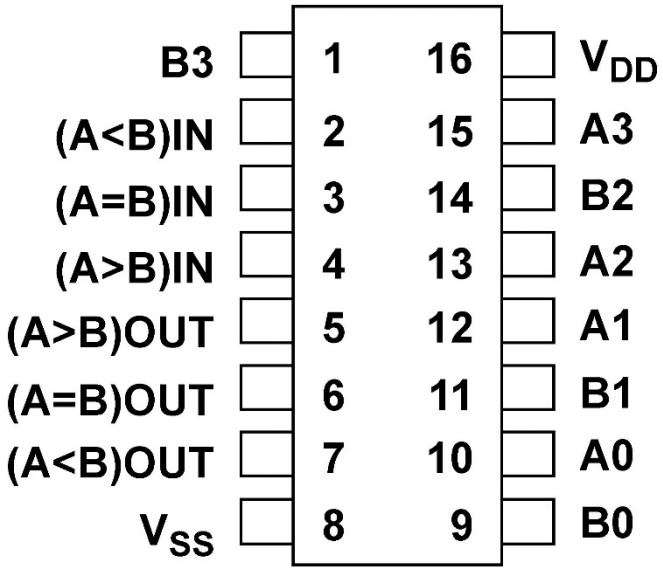


Figure 1: 16-Pin DIP, Top View

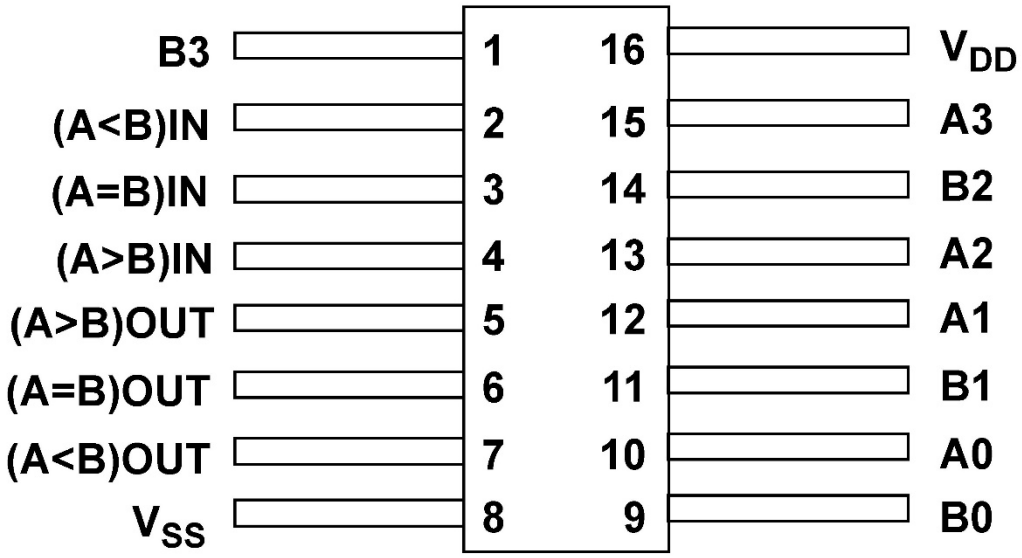
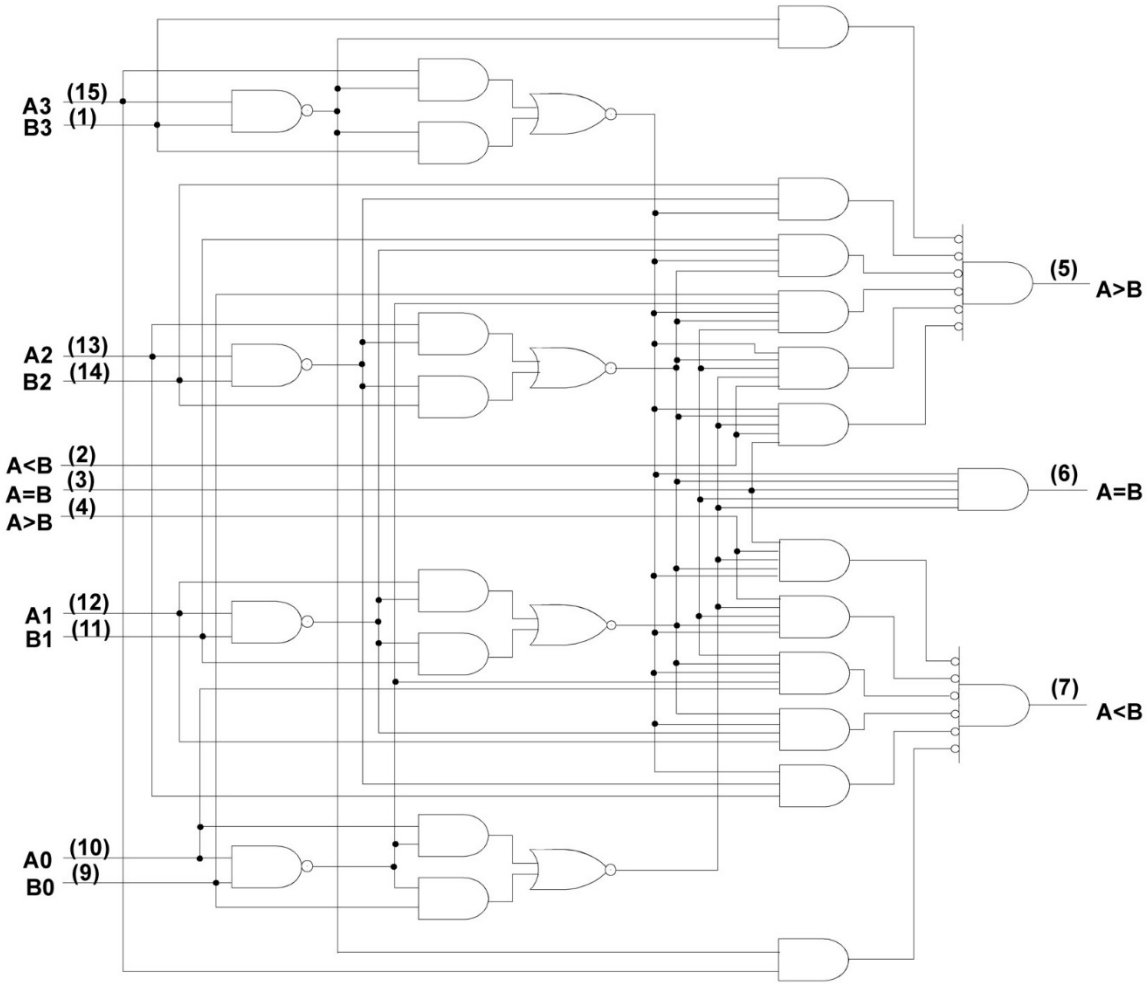


Figure 2: 16-Lead Flatpack, Top View

Function Table

Comparing Inputs			Cascading Inputs				Outputs		
A3, B3	A2, B2	A1, B1	A0, B0	A>B	A<B	A=B	A>B	A<B	A=B
A3>B3	X	X	X	X	X	X	H	L	L
A3<B3	X	X	X	X	X	X	L	H	L
A3=B3	A2>B2	X	X	X	X	X	H	L	L
A3=B3	A2<B2	X	X	X	X	X	L	H	L
A3=B3	A2=B2	A1>B1	X	X	X	X	H	L	L
A3=B3	A2=B2	A1<B1	X	X	X	X	L	H	L
A3=B3	A2=B2	A1=B1	A0>B0	X	X	X	H	L	L
A3=B3	A2=B2	A1=B1	A0<B0	X	X	X	L	H	L
A3=B3	A2=B2	A1=B1	A0=B0	H	L	L	H	L	L
A3=B3	A2=B2	A1=B1	A0=B0	L	H	L	L	H	L
A3=B3	A2=B2	A1=B1	A0=B0	X	X	H	L	L	H
A3=B3	A2=B2	A1=B1	A0=B0	H	H	L	L	L	L
A3=B3	A2=B2	A1=B1	A0=B0	L	L	L	H	H	L

Logic Diagram



Operational Environment[1]

Parameter	Limit	Units
Total Dose	1.0E6	rads(Si)
SEU Threshold[2]	80	MeV-cm^2/mg
SEL Threshold	120	MeV-cm^2/mg
Neutron Fluence	1.0E14	n/cm^2

Notes:

1. Logic will not latchup during radiation exposure within the limits defined in the table.
2. Device storage elements are immune to SEU affects.

Absolute Maximum Ratings

Symbol	Parameter	Limit	Units
V_{DD}	Supply voltage	-0.3 to 7.0	V
$V_{I/O}$	Voltage any pin	-.3 to V_{DD} +.3	V
T_{STG}	Storage Temperature range	-65 to +150	°C
T_J	Maximum junction temperature	+175	°C
T_{LS}	Lead temperature (soldering 5 seconds)	+300	°C
Θ_{JC}	Thermal resistance junction to case	20	°C/W
I_I	DC input current	±10	mA
P_D	Maximum power dissipation	1	W

Note:

1. Stresses outside the listed absolute maximum ratings may cause permanent damage to the device. This is a stress rating only, functional operation of the device at these or any other conditions beyond limits indicated in the operational sections is not recommended. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Limit	Units
V_{DD}	Supply voltage	4.5 to 5.5	V
V_{IN}	Input voltage any pin	0 to V_{DD}	V
T_C	Temperature range	-55 to + 125	°C

DC Electrical Characteristics[7]

(V_{DD} = 5.0V ±10%; V_{SS} = 0V[6], -55°C < T_C < +125°C); Unless otherwise noted, T_C is per the temperature range ordered.

Symbol	Parameter	Condition	MIN	MAX	Unit
V_{IL}	Low-level input voltage[1] ACTS ACS			0.8 .3V_{DD}	V
V_{IH}	High-level input voltage[1] ACTS ACS		.5V_{DD} .7V_{DD}		V
I_{IN}	Input leakage current ACTS/ACS	V_{IN} = V_{DD} or V_{SS}	-1	1	µA
V_{OL}	Low-level output voltage[3] ACTS ACS	I_{OL} = 8.0mA I_{OL} = 100µA		0.40 0.25	V
V_{OH}	High-level output voltage[3] ACTS ACS	I_{OH} = -8.0mA I_{OH} = -100µA	.7V_{DD} V_{DD} - 0.25		V
I_{OS}	Short-circuit output current[2,4] ACTS/ACS	V_O = V_{DD} and V_{SS}	-200	200	mA
I_{OL}	Output current[10] (Sink)	V_{IN} = V_{DD} or V_{SS} V_{OL} = 0.4V	8		mA
I_{OH}	Output current[10] (Source)	V_{IN} = V_{DD} or V_{SS} V_{OH} = V_{DD} - 0.4V	-8		mA
P_{total}	Power dissipation[2,8,9]	C_L = 50pF		2.3	mW/ MHz
I_{DDQ}	Quiescent Supply Current	V_{DD} = 5.5V		10	µA
ΔI_{DDQ}	Quiescent Supply Current Delta ACTS	For input under test V_{IN} = V_{DD} - 2.1V For all other inputs V_{IN} = V_{DD} or V_{SS} V_{DD} = 5.5V		1.6	mA
C_{IN}	Input capacitance[5]	f = 1MHz @ 0V		15	pF
C_{OUT}	Output capacitance[5]	f = 1MHz @ 0V		15	pF

Notes:

1. Functional tests are conducted in accordance with MIL-STD-883 with the following input test conditions: V_{IH} = V_{IH}(min) + 20%, - 0%; V_{IL} = V_{IL}(max) + 0%, - 50%, as specified herein, for TTL, CMOS, or Schmitt compatible inputs. Devices may be tested using any input voltage within the above specified range, but are guaranteed to V_{IH}(min) and V_{IL}(max).
2. Supplied as a design limit but not guaranteed or tested.
3. Per MIL-PRF-38535, for current density ≤ 5.0E5 amps/cm2, the maximum product of load capacitance (per output buffer) times frequency should not exceed 3,765 pF/MHz.
4. Not more than one output may be shorted at a time for maximum duration of one second.
5. Capacitance measured for initial qualification and when design changes may affect the value. Capacitance is measured between the designated terminal and V_{SS} at frequency of 1MHz and a signal amplitude of 50mV rms maximum
6. All specifications valid for radiation dose ≤ 1E6 rads(Si).
7. Maximum allowable relative shift equals 50mV.
8. Power does not include power contribution of any TTL output sink current.
9. Power dissipation specified per switching output.
10. This value is guaranteed based on characterization data, but not tested.

AC Electrical Characteristics[2]

(V_{DD} = 5.0V ±10%; V_{SS} = 0V[1], -55°C < T_C < +125°C); unless otherwise noted, T_C is per the temperature range ordered.

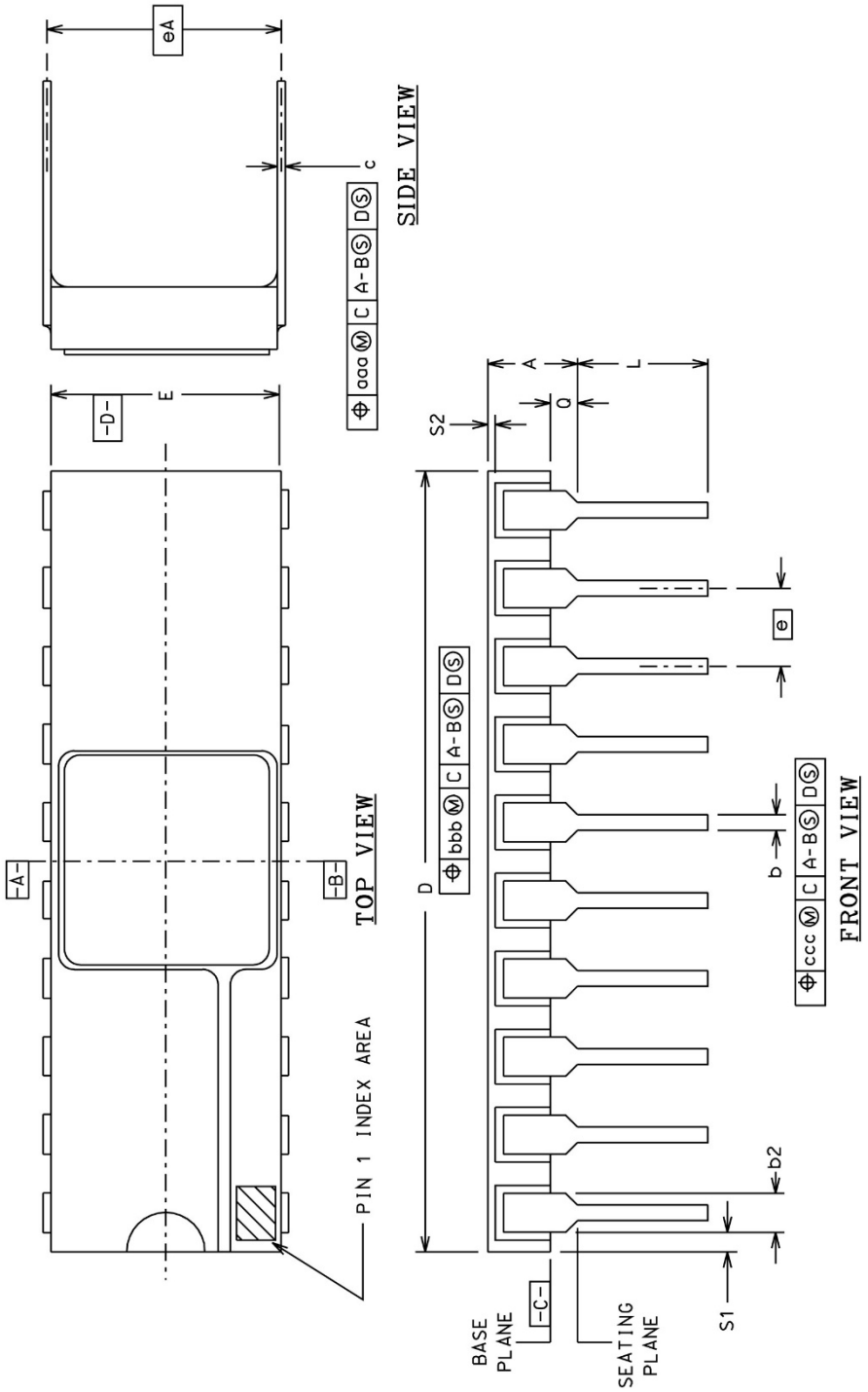
Symbol	Parameter	Minimum	Maximum	Unit
t_{PHL}	An, Bn to $(A<B)_{OUT}$	2	22	ns
t_{PLH}	An, Bn to $(A<B)_{OUT}$	2	16	ns
t_{PHL}	An, Bn to $(A=B)_{OUT}$	2	17	ns
t_{PLH}	An, Bn to $(A=B)_{OUT}$	2	16	ns
t_{PHL}	An, Bn to $(A>B)_{OUT}$	2	18	ns
t_{PLH}	An, Bn to $(A>B)_{OUT}$	2	16	ns
t_{PHL}	$(A<B)_{IN}$, $(A=B)_{IN}$ to $(A>B)_{OUT}$	2	17	ns
t_{PLH}	$(A<B)_{IN}$, $(A=B)_{IN}$ to $(A>B)_{OUT}$	2	15	ns
t_{PHL}	$(A=B)_{IN}$ to (A=B)OUT	2	13	ns
t_{PLH}	$(A=B)_{IN}$ to (A=B)OUT	1	15	ns
t_{PHL}	$(A>B)_{IN}$, $(A=B)_{IN}$ to $(A<B)_{OUT}$	2	17	ns
t_{PLH}	$(A>B)_{IN}$, $(A=B)_{IN}$ to $(A<B)_{OUT}$	2	15	ns

Notes:

1. Maximum allowable relative shift equals 50mV.
2. All specifications valid for radiation dose ≤ 1E6 rads(Si)

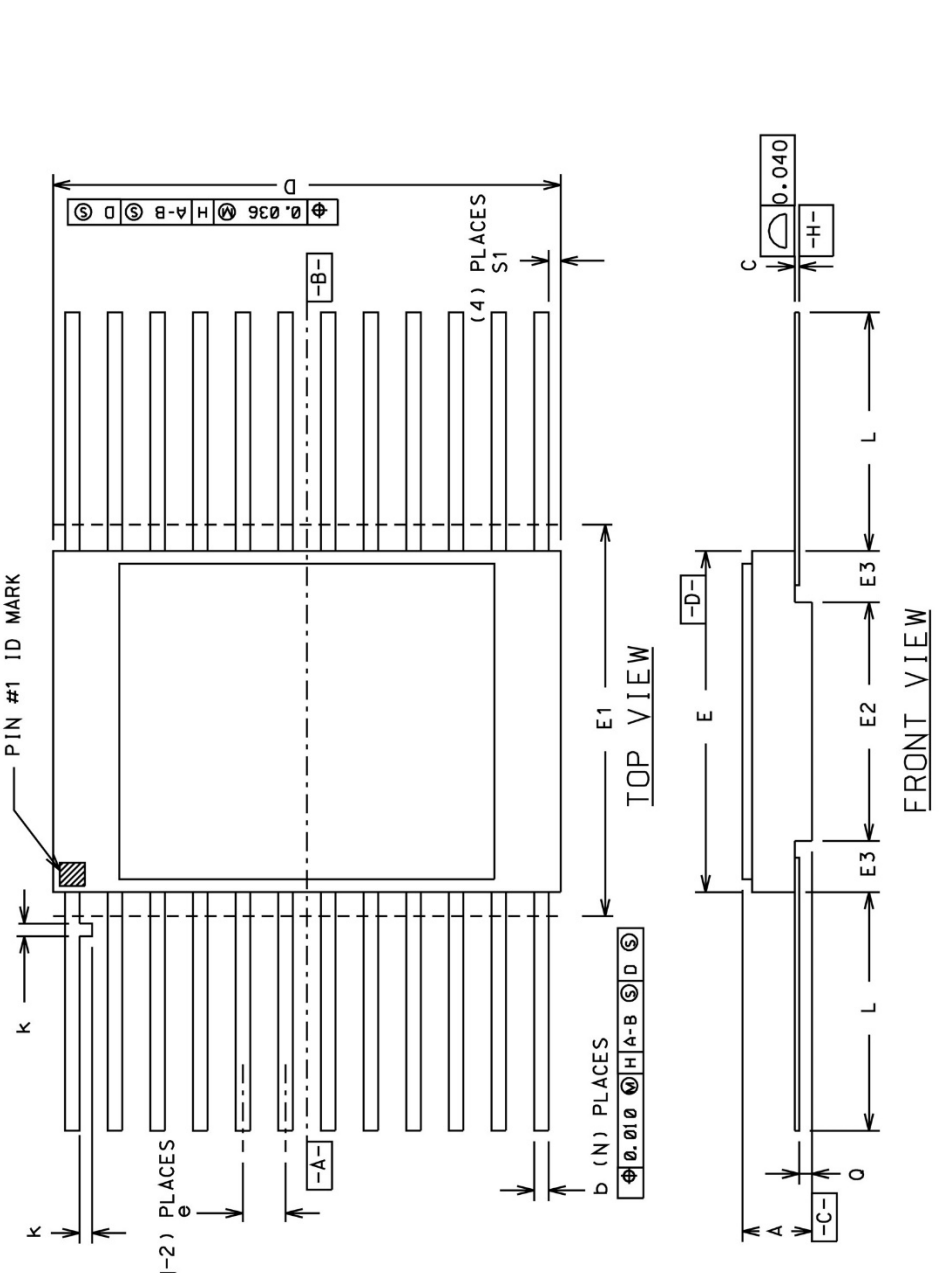
Packaging

Side-Brazed Packages



PKG CONFIG	LEAD COUNT	MIL-STD-1835 DWG CONF C	DIMENSION SYMBOLS																				
			A	b	b2	c	D	E	e	eA	L	Q	S1	S2	aaa	bbb	ccc
-01	14	D-1	0.200 MAX	0.026 0.014	0.065 0.045	0.018 0.008	0.785 MAX	0.310 0.220	0.100 BSC	0.300 BSC	0.200 0.125	0.060 0.015	MIN 0.005	MIN 0.005	0.015 MAX	0.030 MAX	0.010 MAX
-02	16	D-2	0.200 MAX	0.026 0.014	0.065 0.045	0.018 0.008	0.840 MAX	0.310 0.220	0.100 BSC	0.300 BSC	0.200 0.125	0.060 0.015	MIN 0.005	MIN 0.005	0.015 MAX	0.030 MAX	0.010 MAX
-03	20	D-8	0.200 MAX	0.026 0.014	0.065 0.045	0.018 0.008	1.060 MAX	0.310 0.220	0.100 BSC	0.300 BSC	0.200 0.125	0.070 0.015	MIN 0.005	MIN 0.005	0.015 MAX	0.030 MAX	0.010 MAX

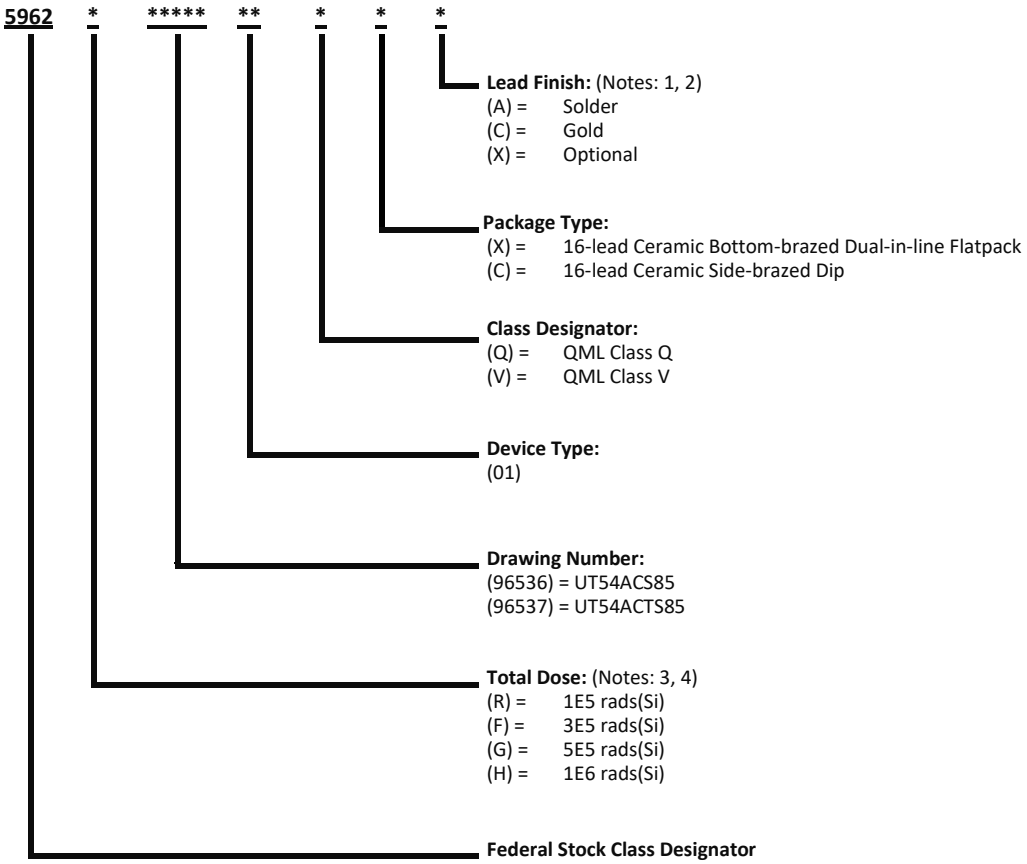
Flatpack Packages



PKG CONFIG	LEAD COUNT	MIL-STD 1835 DWG CONF B	DIMENSION SYMBOLS														
			A	b	c	D	E	E1	E2	E3	e	k	L	Q	S1
-03	14	F-2A	0.115 0.045	0.022 0.015	0.009 0.004	0.390 -----	0.260 0.235	0.290 -----	----- 0.130	----- 0.030	0.050 BSC	0.015 0.008	0.370 0.270	0.045 0.026	----- 0.005
-04	16	F-5A	0.115 0.045	0.022 0.015	0.009 0.004	0.440 -----	0.285 0.245	0.315 -----	----- 0.130	----- 0.030	0.050 BSC	0.015 0.008	0.370 0.250	0.045 0.026	----- 0.005
-05	20	F-9A	0.115 0.045	0.022 0.015	0.009 0.004	0.540 -----	0.300 0.245	0.330 -----	----- 0.130	----- 0.030	0.050 BSC	0.015 0.008	0.370 0.250	0.045 0.026	----- 0.000

Ordering Information

UT54ACS85/UT54ACTS85 SMD Part Number Ordering Information



Notes:

1. Lead finish (A, C or X) must be specified.
2. If an "X" is specified when ordering, part marking will match the lead finish and will be either "A" (solder) or "C" (gold).
3. Total dose radiation must be specified when ordering. QML Q and QML V not available without radiation hardening. For prototype inquiries, contact factory.
4. Device type 02 is only offered with a TID tolerance guarantee of 3E5 rads(Si) or 1E6 rads(Si) and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A and section 3.11.2. Device type 03 is only offered with a TID tolerance guarantee of 1E5 rads(Si), 3E5 rads(Si), and 5E5 rads(Si), and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A.

Revision History

Date	Revision #	Author	Change Description	Page #

Datasheet Definitions

	Definition
Advanced Datasheet	Frontgrade reserves the right to make changes to any products and services described herein at any time without notice. The product is still in the development stage and the **datasheet is subject to change**. Specifications can be **TBD** and the part package and pinout are **not final.**
Preliminary Datasheet	Frontgrade reserves the right to make changes to any products and services described herein at any time without notice. The product is in the characterization stage and prototypes are available.
Datasheet	Product is in production and any changes to the product and services described herein will follow a formal customer notification process for form, fit or function changes.